

HRB0103A

Silicon Schottky Barrier Diode for Low Voltage High Speed Switching, Rectifying

REJ03G0616-0200

(Previous: ADE-208-490A)

Rev.2.00

May 10, 2005

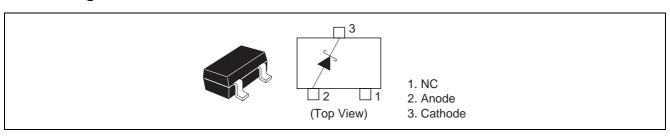
Features

- Low forward voltage drop and suitable for high efficiency forward current.
- CMPAK package is suitable for high density surface mounting and high speed assembly.

Ordering Information

Type No.	Laser Mark	Package Name	Package Code (Previous Code)
HRB0103A	E1	CMPAK	PTSP0003ZB-A
			(CMPAK)

Pin Arrangement



Absolute Maximum Ratings

 $(Ta = 25^{\circ}C)$

Item	Symbol	Value	Unit
Repetitive peak reverse voltage	V_{RRM}	30	V
Average rectified current	lo*1	100	mA
Non-Repetitive peak forward surge current	I _{FSM} * ²	3	А
Junction temperature	Tj	125	°C
Storage temperature	Tstg	−55 to +125	°C

Notes: 1. See Fig.5.

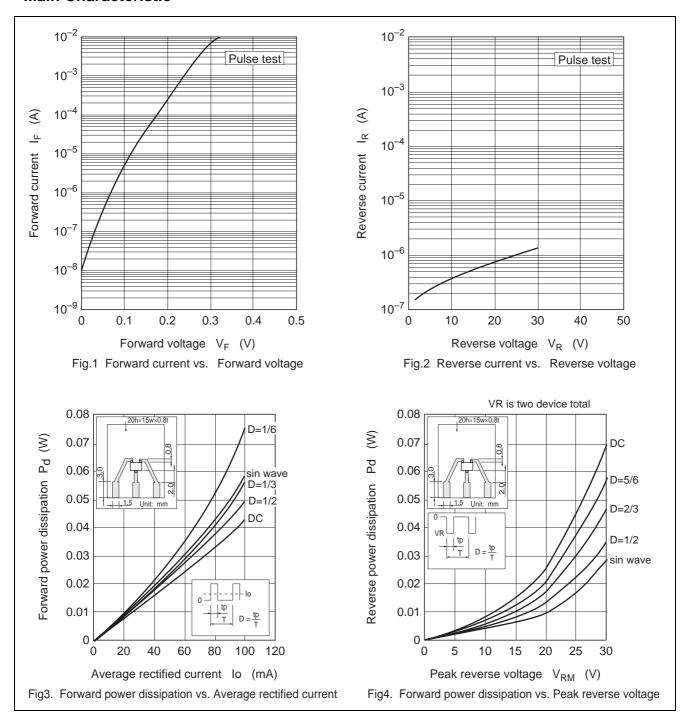
2. 10 ms sine wave 1 pulse.

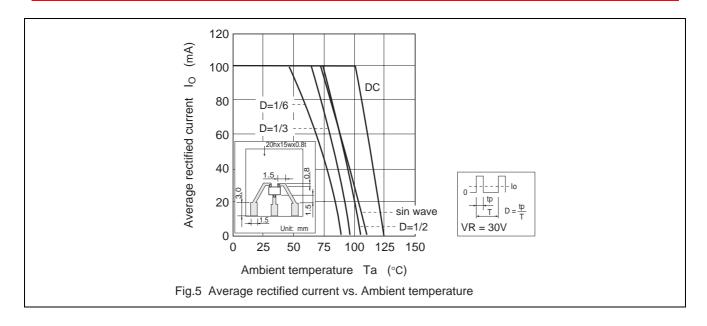
Electrical Characteristics

 $(Ta = 25^{\circ}C)$

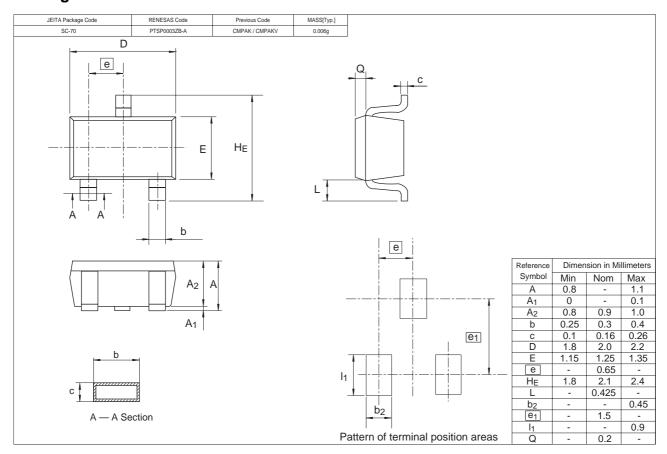
Item	Symbol	Min	Тур	Max	Unit	Test Condition
Forward voltage	V_{F}	1	1	0.44	V	$I_F = 100 \text{ mA}$
Reverse current	I _R	_	_	50	μΑ	$V_R = 30 \text{ V}$

Main Characteristic





Package Dimensions



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